



Material Content Data Sheet



Sales Product Name		BSC030N08NS5		Issued		24. January 2018		
MA#		MA001239702						
Package		PG-TDSON-8-7		Weight*		119.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12690	12690
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
wire	non noble metal	copper	7440-50-8	37.762	31.59	31.63	315835	316246
	noble metal	gold	7440-57-5	0.045	0.04	0.04	373	373
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		716	
	plastics	epoxy resin	-	6.079	5.08		50846	
leadfinish	inorganic material	silicondioxide	60676-86-0	36.646	30.65	35.80	306506	358068
	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12141	12141
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1384	1384
solder	non noble metal	tin	7440-31-5	0.042	0.04		352	
	noble metal	silver	7440-22-4	0.053	0.04		440	
heatspreader	non noble metal	lead	7439-92-1	2.010	1.68	1.76	16815	17607
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.47	9.48	94680	94803
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		187	
*deviation	non noble metal	copper	7440-50-8	22.292	18.64	18.67	186445	186688
	< 10%				Sum in total:		100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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